

# SD1534-08

# RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

医多邦,专业PCB打样工厂,24小时加急出货

- DESIGNED FOR HIGH POWER PULSED IFF, DME, TACAN APPLICATIONS
- 80 WATTS (typ.) IFF 1030 1090 MHz
- **75 WATTS (min.) DME 1025 1150 MHz**
- 50 WATTS (typ.) TACAN 960 1215 MHz
- 8.0 dB MIN. GAIN
- REFRACTORY GOLD METALLIZATION
- EMITTER BALLASTING AND LOW THERMAL RESISTANCE FOR RELIABILITY AND RUGGEDNESS
- INFINITE LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT MATCHED, COMMON BASE CONFIGURATION



## DESCRIPTION

The SD1534-08 is a gold metallized silicon, NPN power transistor designed for applications requiring high peak power and low duty cycles such as IFF, DME and TACAN. The SD1534-08 is packaged in the .280" input matched hermetic stripline flange package resulting in improved broadband performance and a low thermal resistance.

### **ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit	
Vcbo	Collector-Base Voltage	65	V	
V <sub>CES</sub>	Collector-Emitter Voltage	65	V	
V <sub>EBO</sub>	Emitter-Base Voltage	3.5	V	
lc	Device Current	5.5	A	
PDISS	Power Dissipation	218.7	W	
TJ	Junction Temperature	+200	°C	
T <sub>STG</sub>	Storage Temperature	– 65 to +150	°C	

thermal DATA

RTH(j-c)	Junction-Case Thermal Resistance	0.8	°C/W
odf.azsc.com			

# SD1534-08

# **ELECTRICAL SPECIFICATIONS** ( $T_{case} = 25^{\circ}C$ )

### STATIC

Symbol	Test Conditions	Value			Unit	
		Min.	Тур.	Max.	Unit	
ВУсво	Ic = 10mA	IE = 0mA	65	_		V
BVCES	I <sub>C</sub> = 25mA	$V_{BE} = 0V$	65	_		V
$BV_{EBO}$	$I_E = 10 mA$	$I_{C} = 0 m A$	3.5	_		V
ICES	$V_{CE} = 50V$	$I_E = 0 m A$	_	_	5	mA
hFE	$V_{CE} = 5V$	$I_C = 100 \text{mA}$	10	—	200	—

#### DYNAMIC

Symbol	Tast Conditions		Value		
Symbol		Min.	<i>l</i> in. Typ. Max.		om
Роит	$f = 1025 - 1150MHz P_{IN} = 13.5 W V_{CE} = 50 V$	75	_	_	W
GP	$f = 1025 - 1150MHz P_{IN} = 13.5 W V_{CE} = 50 V$	7.5			dB

Note: Pulse Width =  $10\mu$ Sec, Duty Cycle = 1%

This device is suitable for use under other pulse width/duty cycle conditions. Please contact the factory for specific applications assistance.

### PACKAGE MECHANICAL DATA



Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsability for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may results from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectonics.

© 1994 SGS-THOMSON Microelectronics - All Rights Reserved

SGS-THOMSON Microelectronics GROUP OF COMPANIES Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands -Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A